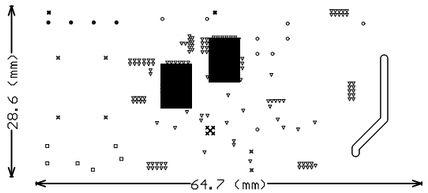
Layer	Name	Material		Thickness	Constant	Board Layer Stack
1	Top Overlay					
2	Top Solder	Solder Resist		(0.4mil)	3.5	
3	Top Layer	Copper		(1.4mil)		
4	Dielectric 2			(10.4mil)	4.4	
5	Mid Layer 1	Copper		(1.4mil)		
6	Dielectric 3			(10.4mil)	4.4	
7	Mid Layer 2	Copper		(1.4mil)		
8	Dielectric 1	Core		(51.2mil)	4.8	
9	Bottom Layer	Copper		(1.4mil)		
10	Bottom Solder	Solder Resist		(0.4mil)	3.5	
11	Bottom Overlay					

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Pad Layer Pair	Hole Tolerance
A	24	13.8110 mil (0.351mm)	PTH	Round	Top Layer to Bottom Layer	
B	4	15.0394 mil (0.382mm)	PTH	Round	Top Layer to Bottom Layer	
C	4	17.2441 mil (0.438mm)	PTH	Round	Top Layer to Bottom Layer	
D	1	21.2598 mil (0.54mm)	PTH	Round	Top Layer to Bottom Layer	
E	1	39.3701 mil (1mm)	PTH	Round	Top Layer to Bottom Layer	
F	1	41.3386 mil (1.05mm)	PTH	Round	Top Layer to Bottom Layer	
G	1	51.1811 mil (1.3mm)	PTH	Round	Top Layer to Bottom Layer	
	36 Total					



1000.00mil

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER MI BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS --> [ ] 1 [X] 2 [ ] 3

[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

Texas Instruments

PROJECT TITLE:

65W USB-PD 2.0 AC-DC Adapter

DESIGNED FOR:

Public Release

FILE NAME:

Mother board.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01622	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = [redacted]ensions	TID #: TIDA-01622		
PLOT NAME = Fabrication Drawing	GENERATED : 5/28/2018 11:17:01 AM	TEXAS INSTRUMENTS	

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ENGINEER: Cheng Liu	LAYOUT BY: Cheng Liu
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.1.12.290